



- 1.) FOD-THR R15/R23—400mW
- 2.) LED R3/R21—Mode 1
- 3.) FOD_CAL R5/R22—178mW/A (1.473V)

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Number: TIDA-00762	Rev: E1	Designed for Public release	Mod. Date: 11/30/2015
SVN Rev. Version control disabled	Assembly Variant: 001	Project Title: Small Form Factor 1W Wireless Power Transmitter	Sheet Title: Power Section (BQ50002)
Drawn By:	File: TIDA-00762E1_SchDoc	Sheet: 1 of 2	Size: B
Engineer: Bill Johns	Contact: http://www.ti.com/support		



DNP
FID1

PCB Number: TIDA-00762
PCB Rev: E1

PCB
LOGO
Texas Instruments



DNP
FID2

DNP
FID3
PCB
LOGO
FCC disclaimer

LBL1

PCB Label
Size: 0.65" x 0.20"

ZZ1

Label Assembly Note
This Assembly Note is for PCB labels only

ZZ2

Assembly Note
These assemblies are ESD sensitive, ESD precautions shall be observed.

ZZ3

Assembly Note
These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.

ZZ4

Assembly Note
These assemblies must comply with workmanship standards IPC-A-610 Class 2., unless otherwise specified.

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